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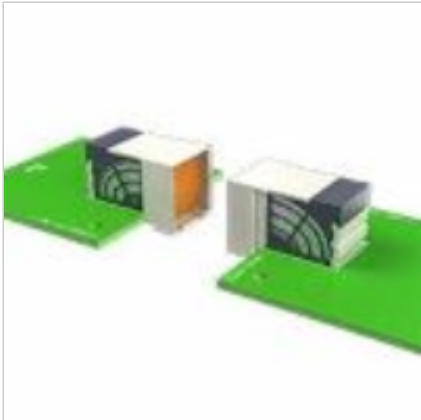
Amphenol

High Speed Connectors



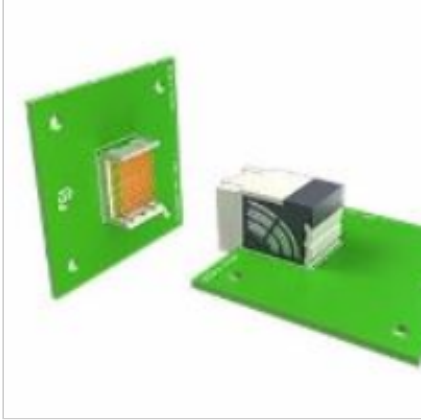
400G QSFP DD SR8

This optical transceiver comes with a maximum link length of 100m on OM4 multimode fiber and is capable of a 400Gb/s data rate with each channel transmitting up to 53.125Gb/s. The module also features outstanding BER and high sensitivity because of its reliable design and excellent coupling efficiency. It is compliant with IEEE 802.3cm, QSFP DD CIMS 4.0, and QSFP DD Hardware 5.1.



AirMax VS2® High-Speed Backplane Connector

AirMax VS2® connectors provide a migration path from AirMax VS® for speeds up to 20Gb/s, providing a margin of safety for typical 802.3ap system performance with the flexibility of an open pin field design. The connectors leverage AirMax VS® and VSe® design features and technology to achieve improved signal integrity and mechanical attributes compared to AirMax VS® connectors.



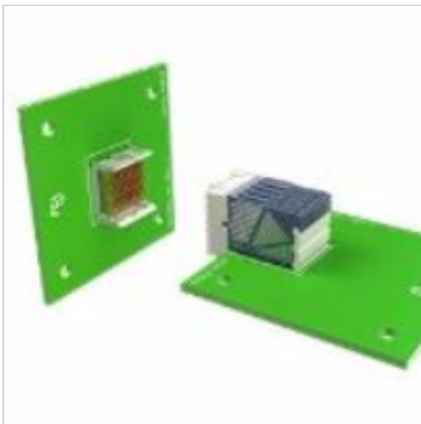
AirMax VSe® High-Speed Backplane Connector

Next-generation AirMax VSe® connectors provide a migration path for up to 25Gb/s per differential pair with the flexibility of an open pin field design. The connectors also feature backward mating-compatible interfaces to existing AirMax VS® connectors with minimal changes to connector footprints.



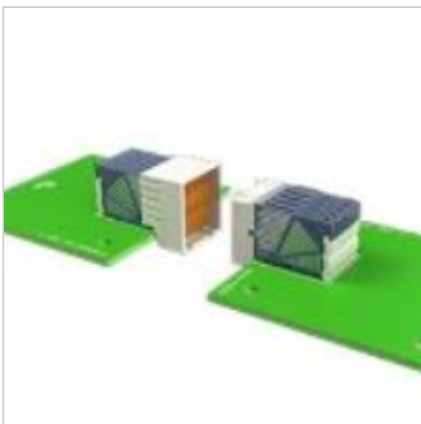
AirMax VS® 85Ohms High-Speed Backplane Connector

HIGH SPEED HARDMETRIC CONNECTOR FOR BACKPLANE SUPPORTING INTEL® QPI
AirMax VS® 85Ohms connectors are optimized to minimize impedance discontinuities and signal loss in 85Ohms channels. The connectors' mating interfaces also satisfy demands for backward compatibility to legacy 100 Ohms product interfaces ensuring a smooth transition to next-generation designs.



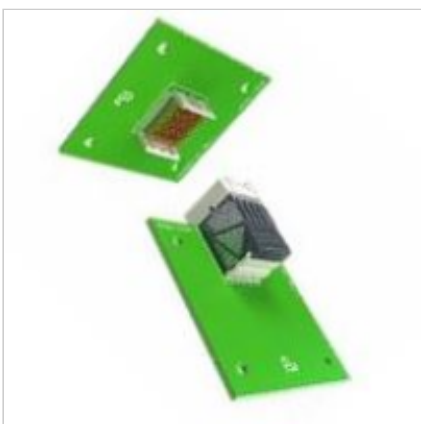
AirMax VS® Connectors for CompactPCI® Serial System

AirMax VS® high-speed signal connectors from Amphenol ICC meet the dimensional and electrical requirements described in the Compact PCI® Serial (PICMG CPCI-s.0) Specification developed by the PCI Industrial Computer Manufacturers Group (PICMG). Connections between a front system or peripheral board and backplane are accomplished using right-angle headers and vertical receptacles.



AirMax VS® Coplanar High-Speed Backplane Connector

AirMax VS® coplanar connectors permit mating two boards in the same plane. The AirMax family includes many coplanar configurations including 3-, 4- and 5-Pair per column connectors with column pitch of 2mm and 3mm. This family also includes 100 Ohms versions for the broad market as well as 85Ohms versions for other computer architectures. These connectors can accommodate 12.5Gb/s applications.



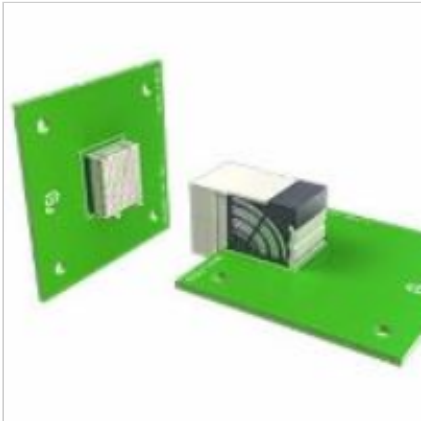
AirMax VS® High-Speed Backplane Connector

AirMax VS® connectors use innovative edge-coupling and air dielectric between adjacent conductors to deliver insertion loss and crosstalk. The AirMax VS® connectors address a broad range of system architectures, including backplane, mid-plane, coplanar, mid-plane orthogonal, cabled backplane, and mezzanine applications.



AirMax VS® Orthogonal High-Speed Backplane Connector

AirMax VS® Orthogonal mid-plane interface features two back-to-back AirMax VS® headers oriented at 90 degrees to each other. The headers connect 16 differential signal pairs through shared vias in the mid-plane, providing a direct, high-speed connection while eliminating traces on the mid-plane. The AirMax VS® Orthogonal mid-plane interconnects can support differential signaling at up to 20Gb/s.



AirMax VS® SBB High-Speed Backplane Connector

AirMax VS® high-speed signal connectors, guide modules, and power connectors meet the dimensional and electrical requirements for the Storage Bridge Bay Mid-plane Interface (SBBMI) to connect bridge/controller cards to the mid-plane in a drive enclosure. It comes with high-speed serial data rates that can scale from 2.5Gb/s to 12.5Gb/s without requiring the redesign of a basic platform.



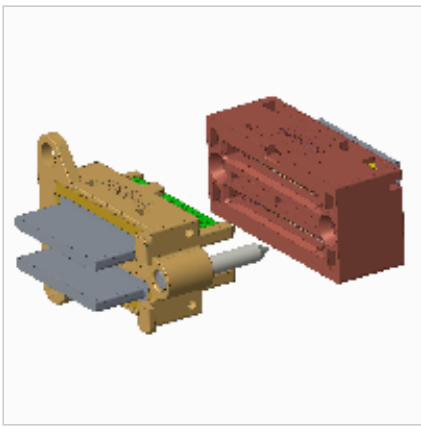
Aptera™

The Aptera™ connector meets difficult electronic packaging challenges with a high-speed interconnect designed specifically for space-constrained areas without impeding airflow. Aptera's™ pin assignments are not predetermined, providing more flexibility when it comes to PCB routing design. It features low crosstalk that supports 6.25Gb/s data rates.



ASGTC-Q

ASGTC-Quadrax is a special circular bayonet coupling connector for data line transmission in RMT application, It's IP67 protection and with a self-locking system specially designed in order to get heavy duty application, Q-contacts with the protection of copper body and multipoints band in female contact to provide to 360° shielding.



Blind Mate MCIO

Amphenol's Blind Mate MCIO is designed for high speed and high density. It can support PCIe Gen5, and is scalable to PCIe Gen6. We designed Blind Mate MCIO with a guide pin to prevent damages during plug in and plug out. Blind mate MCIO has a robust mechanical design, and the connector can be fixed by a screw-on panel.



CA Series - Connectors

CA Series™ high performance 32 Gb/s+ compression mount connectors & interposers offer exceptional signal integrity and high density for applications like high-speed backplane, mezzanine, edge card, and optical at a 0.4 mm pitch in a pure vertical interface without offset requirements. These connectors offer enhanced reliability even under extreme conditions.



Centaur Connectors

Combines our extensive legacy of Mil-Spec connectors with the latest in high-speed technology, providing both a durable and high-bandwidth system that supports data rates up to 56 Gbps in a lightweight, aluminum MIL-DTL-38999 shell.



CFP2

Amphenol's CFP2 series offers a 104 position, 0.6mm pitch connector designed to be compatible with 100Gb/s Form Factor Pluggable (CFP) Multi-Source Agreement for Ethernet and other applications. Rated for 25Gb/s per channel with resonance dampening for improved signal integrity, CFP2 has up to 60% lower power consumption versus CFP.



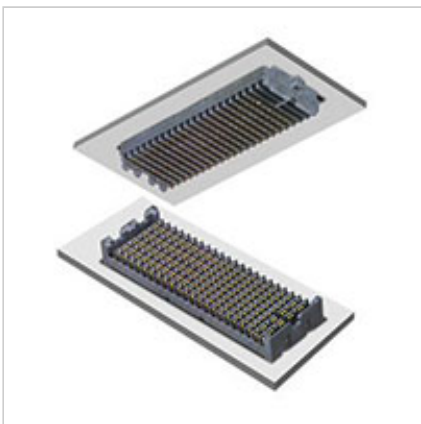
CFP4

Amphenol's CFP4 series offers a 56 position, 0.6mm pitch connector, and is used in multi-hundred Gb/s systems. Rated for 25Gb/s per channel with resonance dampening for improved signal integrity, CFP4 has up to 60% lower power consumption versus CFP. The CFP4 series includes a plug connector on the mating interface to improve accuracy and aid in delivering high-speed performance.



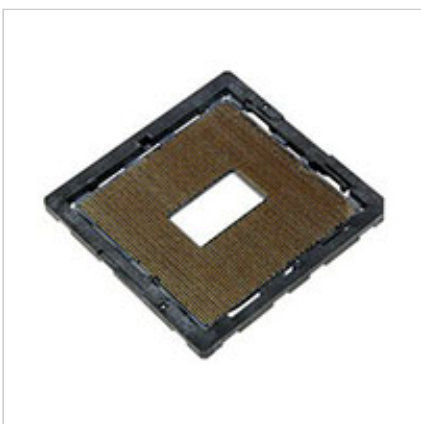
CFP8

Amphenol's CFP8 interconnect system has 124 contacts per port, with a 0.5mm contact pitch and 16 high-speed channels. It is rated for 28Gb/s per channel with resonance dampening for improved signal integrity. It is comprised of insert molding assemblies for top side contacts and Press-Fit cage assemblies.



Chameleon®

With performance speeds up to 25 Gbps+, Chameleon meets the demand for faster, smaller, and more compact connector solutions. With stack heights from 6mm to 10mm in 1mm increments, pin counts from 40 to 500+, and pair counts from 16 to 160, Chameleon provides you with a ready platform to easily change and adapt to your design requirement.



cLGA®

The Amphenol ICC cLGA® land grid array socket system was designed to bring conventional connector material construction to high-performance, low-cost chip-to-board applications. cLGA® sockets are used in applications ranging from handheld computer products to supercomputer systems. The cLGA® socket is fully qualified under Telcordia GR-1217-CORE specifications.



μCom 10 Gb+

μCom-10Gb+ Series connector is designed to meet the latest market trends of the industry: miniaturization and high speed. μCom-10Gb+ design of 4 twisted data pairs insulated throughout the entire connector results in a performance that exceeds IEEE 802.3an-2006 specifications for 10GBASE-T Ethernet and TIA/EIA-568-C.2 Cat6 standards.



μCom USB3.0

Miniature multi-pin USB3.0 connectors for harsh environments.



Cool Edge 0.80mm Hybrid Power & Signal Connectors

Cool Edge Hybrid Power and Signal connectors provide a one-piece high speed and high power card-edge package. These versatile solutions address multiple standards like PCIe, SAS, SATA, and offer multiple BTB configurations such as mezzanine, coplanar, and midplane/backplane. Moreover, the connectors are designed as Open Pin Field and are hot-plug capable.



Cool Edge 1.00mm PCIe Connectors

Cool Edge PCIe® connectors bring high-speed PCIe® support into a one-piece card edge package with 16GT/s Gen 4 and 32GT/s Gen 5 capabilities. Slim connector design saves space on the motherboard while facilitating other higher-density applications. These connectors come with a simple housing design with an overall reduced footprint, providing additional benefits over standard PCIe® CEM solutions.



Cool Stack 0.80mm Hybrid Power & Signal Connectors

Cool Stack Hybrid Power and Signal connectors provide one-piece high speed and high power solutions while addressing multiple networking standards like PCIe, and SAS/SATA. It offers a maximum current rating of 16A per power pin, which aids in supporting applications with medium power requirements.



cStack™

The Amphenol ICC cStack™ high-speed solder-less interconnect solution provides limitless flexibility for board-to-board mezzanine applications and board-to-board stackable and coplanar applications when terminated to a flex circuit.



CXP

CXP connector comes in a one-piece Press-Fit assembly that provides one-step placement to the board to accommodate single, ganged, or stacked connector configurations in high-density requirements. CXP system has twelve channels for up to 20 Gbps, resulting in 240 Gbps of total bandwidth. This allows our CXP to go beyond the 100 Gigabit Ethernet IEEE 802.3ba & the InfiniBand CXP12x QDR standards.



D38999 Connectors with Coaxial, Concentric Twinax, and Triax Contacts

MIL-DTL-38999 connectors are ideally suited for shielded contacts for high-performance, high-speed interconnection applications. Insert arrangements can incorporate: coax (sizes 8, 12, and 16); twinax (sizes 8 and 12); and triax contacts (sizes 8, 10, and 12).



D38999 Connectors with Quadrax, Differential Twinax Contacts

D38999 Series III Connectors are ideally suited for the incorporation of shielded contacts for high-performance, high-speed interconnection applications. Uses size 8 high-speed Quadrax and Differential Twinax contacts. A wide selection of connector shell styles and sizes are available. Transition adapters can be used to attach connectors with Quadrax or Differential Twinax contacts to PCBs.



DensiShield® High Speed Cable Connector

Amphenol's DensiShield® I/O system is designed to support the transmission of high-speed, serial differential signals while taking customers' equipment packaging requirements into consideration. Combining high density, mechanical robustness, and ease of PCB assembly with excellent shielding and signal integrity performance means that system designers no longer have to compromise.



Double Density Cool Edge 0.80mm Connectors and Cable Assemblies

The 0.80mm pitch DDCE connectors and cable assemblies offer a compact design with 2 rows of contacts. This highly configurable single-piece connector can accommodate both high-speed and low-speed signal and power. This hybrid connector reduces more than half of the PCB footprint when compared to 1.00mm PCIe Cool Edge. It supports PCIe Gen 5 and is designed for multiple Add-In- Card thicknesses.



DSFP 56G PAM4 SMT Connector

DSFP SMT Connectors offer dual high-speed lanes operating at 28Gb/s NRZ and 56Gb/s PAM-4 for a 50G & 100G aggregated bandwidth solution. It has additional 2 pins compared to the SFP/SFP+ family, which enables it to have a second high-speed channel with an identical connector form factor. The DSFP shares the same unique mating interface and EMI cage dimensions as the whole range of SFP/SFP+ cages.



Elite®

ULTRA-HIGH DENSITY BACKPLANE INTERCONNECT SOLUTION Ultra-High density 56+ Gbp/s PAM4 interconnect platform utilizing proven press-fit technology and a single wafer design optimized for traditional backplane, direct orthogonal, and cable design solutions.



EN4165 / SIM with Module RJ45-Cat6a 10Gb

Amphenol Air LB France's SIM module for RJ45 Cat6a 10Gb can be used with the whole range of EN4165 / SIM Monomodule connectors. Available for cable-to-cable or cable-to-PCB applications. Rear accessories are available to provide a sealed connection.



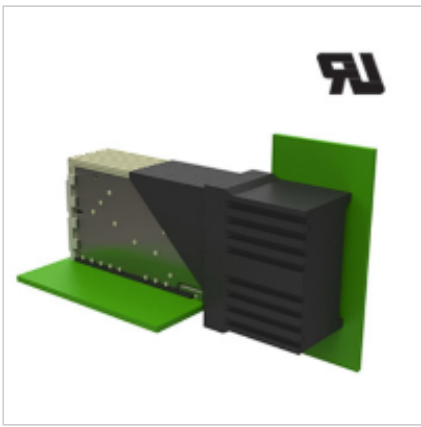
eQSFP

The eQSFP interconnect system is comprised of a 38 position 0.8mm pitch SMT connector, and a press-fit cage. With four channels of data in one pluggable, the system interface is capable of transferring data up to 28 Gbps/Channel and replacing up to 4 standard SFP+ receptacles. Supporting standards include Gigabit Ethernet, InfiniBand, and SONET/SDH with different data rate options.



ExaMAX2® 112Gb/s High-Speed Backplane Connector

The ExaMAX2® backplane connector system supports 112Gb/s PAM4 industry specifications. It maintains mating interface compatibility with previous ExaMAX products to allow cost/performance flexibility for designers. The mating interface and connector design are optimized to support the demanding electrical and mechanical requirements of 112G systems. ExaMAX2 delivers industry-leading SI performance.



ExaMAX+® High Speed Backplane Connector System

The ExaMAX+® backplane connector system is designed to meet 56Gb/s PAM4 industry specifications with plenty of SI margin while maintaining mating interface compatibility with previous ExaMAX® products. The optimized connector design delivers superior signal integrity performance resulting in lower crosstalk noise and higher insertion loss-to-crosstalk ratio.



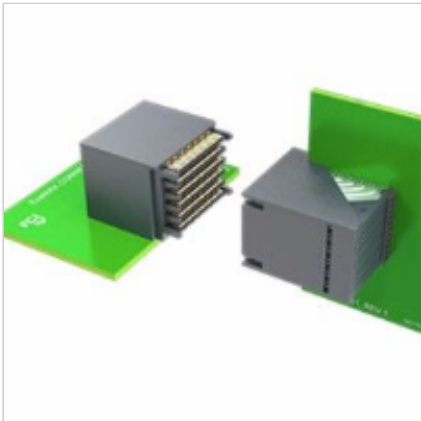
ExaMAX® 56Gb/s High-Speed Backplane Connector 85Ohm

The ExaMAX® 85Ohms backplane connector system is designed for higher bandwidth applications from 25Gb/s to 56Gb/s. Optimized connector design delivers superior signal integrity performance resulting in low crosstalk noise and low insertion loss. Each signal wafer incorporates an innovative one-piece, embossed ground structure to improve crosstalk performance through 56Gb/s.



ExaMAX® 56Gb/s High-Speed Backplane Connector 92Ohm

ExaMAX® backplane connector system is designed for higher bandwidth applications from 25Gb/s to 56Gb/s. The optimized connector design delivers superior signal integrity performance resulting in low crosstalk noise and low insertion. Each signal wafer incorporates an innovative one-piece, embossed ground structure to improve crosstalk performance through 56Gb/s.



ExaMAX® 56Gb/s High-Speed Orthogonal Connector

The ExaMAX® high-speed orthogonal connector system is designed to enable superior 25Gb/s electrical performance and provide a path to 56Gb/s in anticipation of further increases in bandwidth requirements. The 6-Pair orthogonal right-angle header connector solution further expands the range of applications supported by the ExaMAX® connector system.



ExaMAX® VS High-Speed Backplane Connector

The ExaMAX® VS backplane system is a scalable, cost-optimized connector system designed for higher bandwidth applications up to 25Gb/s. The high-performance connector system provides both mechanical robustness and superior signal integrity, minimizing channel performance variation for every differential pair.



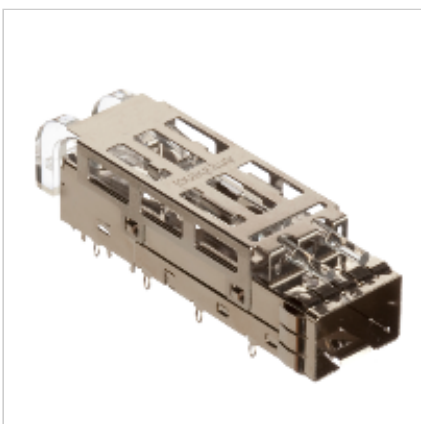
ExaMEZZ® 56Gb/s High Speed Mezzanine Connector System

The ExaMEZZ® connector is designed to enable superior 25Gb/s electrical performance and provide a path to 56Gb/s in anticipation of further increases in bandwidth requirements and high-speed signaling. ExaMEZZ® connectors feature a revolutionary beam-on-beam contact interface that minimizes the residual stub for improved signal integrity performance.



ExpressPort® QSFP+

Amphenol's ExpressPort® QSFP+ interconnect system is comprised of a 38 position 0.8mm pitch SMT connector, & a press-fit cage. With four channels of data in one pluggable, the system interface is capable of transferring data up to 16Gb/s per Channel, & replacing up to 4 standard SFP+ receptacles. These features result in greater port density & overall cost savings over traditional SFP+ products.



ExpressPort® SFP+

Amphenol's ExpressPort® SFP+ interconnect system provides data transfer speeds of up to 16Gb/s. The design of the ExpressPort® SFP+ connector minimizes impedance discontinuities & reflections at high data rates & provides a 10-20dB improvement in Near-End Crosstalk. ExpressPort® SFP+ cage construction features EMI shielding available in the form of metal spring fingers or elastomeric gaskets.



ExtremePort™ Flash Connector

Amphenol introduces the next-generation OverPass™ solution - ExtremePort™ Flash. The 0.60mm pitch connector comes with an extremely low profile design capable of transmitting a high-speed signal up to 56G PAM4, and allows much greater signal path lengths while maintaining SI performance when compared to conventional PCB routing methods.



ExtremePort™ QSFP DD 112G Connectors

Amphenol's ExtremePort™ QSFP DD 112G interconnect system is comprised of a 76 position, 0.8mm pitch connector built for use in high-speed serial applications. Each port supports up to 800Gb/s in aggregate over an 8 x 112Gb/s electrical interface. The cage and connector design provides backward compatibility to QSFP56...



ExtremePort™ QSFP+

Amphenol's ExtremePort™ QSFP+ interconnect system is comprised of a 38-position, 0.8mm pitch connector built for use in high-speed serial applications. Each port offers 4 channels to increase port density which allows for more board real estate and cost-optimized solutions. The ExtremePort™ QSFP+ connector supports next-generation 200G+ applications and transmits up to 56Gb/s PAM4 per channel.



ExtremePort™ SFP+

Amphenol's ExtremePort™ SFP+ interconnect system is comprised of a 20-position hot-swappable I/O connector enclosed in a metal cage mounted to a host PCB. It supports up to 56Gb/s PAM4 aggregate bandwidth with backward compatibility for next-gen Ethernet & Fibre Channel applications. ExtremePort™ SFP+ connector shares the same unique mating interface & EMI cage dimensions as the SFP+ form factor.



ExtremePort™ Swift Connectors

Amphenol has developed the ExtremePort™ Swift connector which is used in the application of PCIe® Gen5 signal NRZ 32GT/s, UPI 2.0 24GT/s, 24Gb/s SAS signal. With 0.6mm contact pitch, ExtremePort™ Swift solutions are smaller than mainstream connectors in the current market to save space in the end device.



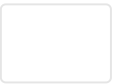
ExtremePort™ Z-Link

Amphenol introduces the SFF-TA-1002 standard solution - ExtremePort™ Z-Link, which is a 0.60mm pitch connector that comes with a slim form factor design, capable of transmitting a high-speed signal up to 56G PAM4, and allowing much greater signal path lengths while maintaining SI performance when compared to conventional PCB routing methods.



GCB-M Modular Reverse Bayonet

Reverse Bayonet modular connector GCB-M, as per VG95234, housing size 32, to take up to 4 modules as per EN4165 for contacts: AWG 23- AWG8, FO contacts (MTP, MPO), RJ45, coax, quadrax contacts.. More than 230,000 various pole arrangements are possible. These connectors are also available in Marinebronze and Zinc-Tin versions.



High Speed Connectors



GT Quadrax

This series, featuring high-speed contacts, ruggedized harsh environment protection, metal reverse bayonet coupling, signal connector. With four Quadrax contacts per connector and bandwidth up to 1.25 GHz, a data rate exceeding 2.5 Gbps with a standard operating temperature from -55°C to +125°C.



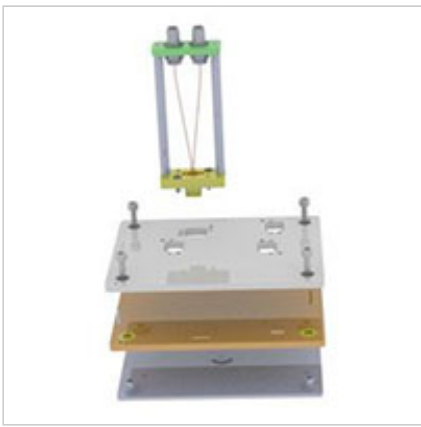
HSC Connector System

HSC connector system is a fully shielded interconnect system that supports data rates up to 1Gb/s and more. With 0.50mm square terminals, it allows a lighter and smaller connector design. The comprehensive shielding of these connectors provides enhanced EMI performance. It is designed for automotive applications like LVDS, camera, USB, and IEEE 1394.



HSD (High Speed Data) Connector System

HSD connector system is a fully shielded interconnect system that can be used with shielded twisted quad cables. It has a high-performance digital system for low-voltage differential signals which prevents interference from crosstalk and external sources. It has the minimum size to satisfy global automotive requirements such as LVDS camera, USB, and IEEE 1394 applications.



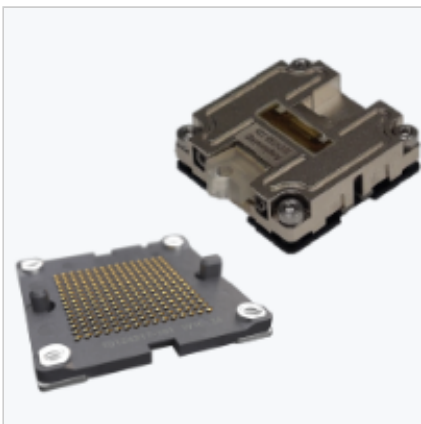
ICFP

Amphenol's ICFP offers 50 Ohms access to IC contact pads and signal paths on an IC circuit footprint. This solution is simple to manipulate, cost-effective, and time-saving alternative to expensive X-Y tables and fragile planar probes for Engineers who may need to probe multiple signals at once.



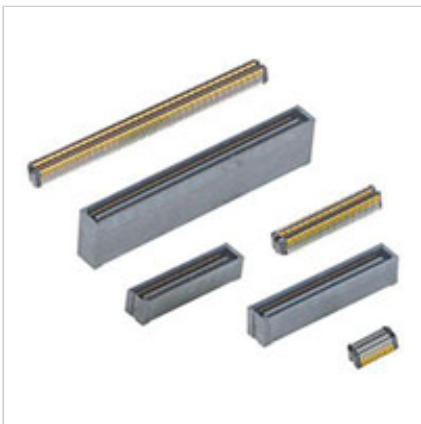
InfinX®

The InfinX® high-speed mezzanine connector solution is designed to meet the needs of 25+Gb/s applications. Available in 4- and 6-Pair configurations, InfinX is your best choice for high-speed board-to-board applications. InfinX supports from 10mm to 42mm stack heights and provides unparalleled reliability and signal integrity with its patented Resonance Dampening Technology.



Leap-AHRD

The 300Gb/s Leap-AHRD High-Speed Optical Module is faster, smaller, more cost, and power-efficient than most conventional data center interconnects. The on-board transceiver rugged device is capable of speeds up to 25Gbps and distances up to 100 meters. The optical cable can be routed above and around other components in the integrated heat-sink design.



Lynx™

The Lynx™ connector is a flexible 0.6mm pitch solution designed for high speed and density differential or single-ended signaling BTB applications. Lynx™ has a robust contact design tolerant of misalignment, enables a reliable connection, and supports blind mating. This connector provides designers with a readily available 85Ω solution to meet a wide variety of application needs, including PCI.



Lynx™ QD

Optimized for differential pair signaling, Lynx™ QD sets a new standard for density and flexibility that offers an innovative, high-performance interconnect with PCIe® Gen 5 support. Lynx™ QD supports data rates of 56 Gb/s PAM4 and provides a 4-row differential signaling structure, in a compact 2-row footprint.



Micro Cool Edge NF1/NGSFF 0.50mm Connectors

Micro Cool Edge NF1/NGSFF 0.50mm is a new small form factor card edge connector designed for enterprise and data center SSD (Solid State Drive) servers. It supports NF1/NGSFF (Next Generation Small Form Factor) which can double storage capacity and enable front side service within server systems compared to the M.2 standard.



Mini Cool Edge IO

Amphenol ICC introduces the next-generation OverPass™ solution - Mini Cool Edge IO. The 0.60mm pitch connector comes with a slim form factor design, capable of transmitting a high-speed signal up to 56G PAM4, and allowing much greater signal path lengths while maintaining SI performance when compared to conventional PCB routing methods.



Mini-SAS

The Mini-SAS external I/O connector consists of a die-cast metal cage and a Compact Multi-Lane SMT connector. It supports Fiber Channel & InfiniBand standards, making it the perfect solution to the ever-growing demand for high-speed mass storage systems, servers & storage area networks. Providing four serial send/receive channels/ports, this connector provides signal speeds of 6 Gbps/channel.



Mini-SAS Connectors

Amphenol's external mini-SAS / SATA connector, cage, and cable assembly system solution addresses the storage industry's demand for more compact, high-speed serial I/O interfaces that also support evolving signal speed requirements.



Mini-SAS HD

Mini-SAS High-Density receptacle is the next-gen SAS system; the SAS 2.1 standard meets SAS-3 next-gen speed & density requirements that provide faster data transmission & more bandwidth for end users. The low-profile system provides 4X and 8X cable-plug options & the external I/O connectors include eight sideband signals per 4X port, 1x4 configuration for up to 192Gb/s of total bandwidth.



Mini-SAS HD Internal

NEXT-GENERATION SAS STORAGE INTERFACE Amphenol Mini-SAS High-Density connector system is the next-generation SAS system that provides faster data rates and more bandwidth. It provides double the port density of current Mini-SAS connectors with 1x1, 1x2, and 1x4 port options.



MRC (Multi-Media Ruggedized Connectors)

Micro-miniature solution ideal for communications systems running Gigabit Ethernet, USB 2.0/USB 3.0, HDMI, and 10 Gigabit Ethernet when specified and designated to a specific configuration.



M-Series™ 56

56GB/S HIGH-SPEED MEZZANINE BGA CONNECTOR SYSTEM Leveraging proven technologies, including an industry-leading BGA design, offering superior self-aligning and self-leveling. With a next-generation differential pair contact design for up to 56Gb/s NRZ and 112Gb/s PAM4 performance.



NeXLev®

Amphenol's NeXLev® is an established and proven high-density parallel board-to-board connector solution to meet current bandwidth demands in many mezzanine applications. NeXLev delivers a robust, market-proven connector in a small footprint. NeXLev connectors contain either 10, 20, or 30 wafers, with each wafer containing 10 real signal contacts. NeXLev features data rates up to 12.5Gb/s.



OCS - Oval Contact System Connectors

High-speed data transmission up to 10 Gbps per pair. MIL-DTL-38999 shell styles are available from size 9 to 25. A wide variety of insert arrangements is available. Patterns range from (1) to (21), 100 Ohm differential pairs capable of delivering data transfer speeds of 10Gbps per pair. PCB Tails contacts available, sockets only, epoxy backfilled.



Octonet Contacts

Size 8 Octonet Contacts for MIL-DTL-38999 Series III connectors. Available in size 8 crimp termination style, including PC tails. Can be installed in existing size 8 Quadrx cavities. Meets performance specifications of CAT-6A cable. Overall higher bandwidth than standard CAT5E Quadrx-supports up to 4.0 Gbps per pair. 10G Ethernet compliant.



OSFP

Amphenol's OSFP interconnect system has 60 contacts per port, with a 0.6mm contact pitch and 8 high-speed channels. The OSFP footprint is optimized for signal integrity performance and built for use in high-speed serial applications. The connector is enhanced for low crosstalk and has ground commoning for resonance dampening. It is also designed for 1U applications.



OverPass™ QSFP+

Amphenol's OverPass™ QSFP+ interconnect system is comprised of a 38-position, 0.8mm pitch connector built for use in high-speed serial applications. The OverPass™ QSFP+ connector supports next-generation 200G+ applications and transmits up to 56Gb/s PAM4 per channel. It features a stamped and formed contact design providing improved mechanical durability.



Paladin® 112Gb/s Backplane Connector

AMPHENOL'S GAME-CHANGING 112Gb/s BACKPLANE INTERCONNECT TECHNOLOGY. Paladin's® revolutionary architecture sets the benchmark for signal integrity performance in backplane interconnects. Exhibiting smooth linear transmission beyond 40GHz, the lowest crosstalk in the market, and consistent SI performance over its entire mating range.



Paladin® Cabled Backplane

Cable Backplane Systems is part of Amphenol's Highspeed Backplane Product business, dedicated to developing and manufacturing cabled backplane solutions for next-generation system architectures. Our customers are leading providers of data center switches and routers, enterprise servers, and high-performance computers.



Paladin® HD 112G Backplane Interconnect System

The Paladin® HD interconnect system provides world-class bandwidth through industry-leading density at 112GB/s performance, supporting up to 144 differential pairs orthogonally within 1U spacing. Paladin HD utilizes a balanced pair structure; built with individually assembled and discretely shielded differential pairs which have a revolutionary hybrid board attachment for maximized density.



QSFP DD

Amphenol's QSFP DD interconnect system is comprised of a 76 position, 0.8mm pitch connector built for use in high-speed serial applications. Each port supports up to 400Gb/s in aggregate over an 8 x 50Gb/s electrical interface. It is one of the industry's leading multi-lane pluggable form factors used across Ethernet, Fibre Channel, and InfiniBand.



RCx

RCx is a simple, high density, low cost, passive connector and cable system specifically designed for intra-rack connectivity of 25 Gb, 50 Gb, and 100 Gb Ethernet allowing for a seamless intra-rack switch to adapter deployments. RCx is density optimized and can accommodate more than 128/25 Gbps lanes in a RU faceplate.



Rectangular Connectors with High Speed Contacts

Offer several advantages for high data transfer rates, low power consumption, and excellent EMI compatibility. Variety of plated, aluminum shell styles available. Quadrax, Split Pair Quadrax, or Differential Twinax available. Board Level connectors can incorporate straight or PCB Tails right angle, or straight compliant tail contacts.



RJF 544

RJF 544 allows you to use an Ethernet Class D / Cat 5e connection for 10 BaseT, 100 BaseTX, or 1000 BaseT networks in harsh environments. With the patented RJStop® system you can use a standard RJ45 cordset in a protective composite plug which will protect it from shocks, dust, and fluids. No hazardous on-field cabling and grounding!



RJF Cat5e, Cat6, Cat6A (New Cat6A version)

RJF Cat6A allows you to use an Ethernet Class Ea / Cat. 6A connection for 10 BaseT, 100 BaseTx, 1000 BaseT, or 10 G BaseT up to 500 MHz networks in harsh environments. With the patented RJStop system you can use a standard RJ45 cordset in a metallic plug that will protect it from shocks, dust, and fluids. No hazardous on-field cabling and grounding!



RJF RB

Ethernet RJ45 connection system for industrial harsh environment.



RJF TV ATEX Zone 2 versions

Explosion-proof Ethernet solutions for Zone 2 that are low-power non-sparking connectors.



RJF TV Cat5e, Cat6, Cat6A – Reduced flange receptacle

Derived from standard RJF TV, Reduced Flange RJF TV is ideal for applications where small dimensions and lower weight are critical in harsh environments. RJFTV Reduced flange receptacle is available in Cat5.e, Cat.6 and Cat6A. With the patented RJStop system you can use a standard RJ45 cordset in a metallic plug that will protect it from shocks, dust, and fluids.



R-VPX

R-VPX is a ruggedized, high-speed, board-to-board interconnect system capable of data rates in excess of 10 Gbps, meeting and exceeding VITA 46 standards. This connector system gives users modularity and flexibility by utilizing PCB wafer construction with customized wafer-loading patterns.



R-VPX Evolution

R-VPX High-Speed Evolution Modules are capable of 16+ Gbps data rate transfer performance. Evolution meets the performance requirements of VITA 46 & 47 while still intermateable with existing VITA 46 backplane connectors. This connector system is optimized for speed and ruggedized to handle harsh environment requirements in military applications across the board.



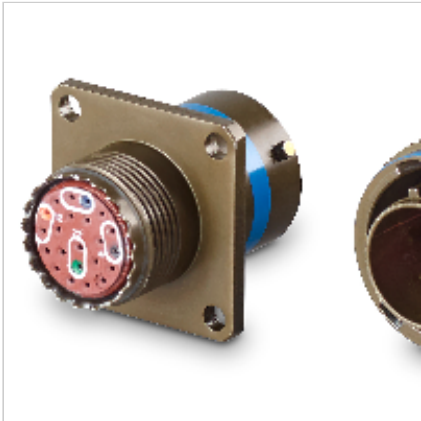
R-VPX Evolution 2.0

R-VPX Evolution 2.0 is the next generation of high-speed ruggedized backplane connectors. Evolution 2.0 series connectors are designed, optimized and qualified to data rates in excess of 32Gb/s making these connectors the fastest VITA 46.30 connectors in the world. They are tested to VITA levels and are backward intermateable with R-VPX, R-VPX EVO 1, and VITA 46 qualified connectors.



SFP

Amphenol's SFP product family supports applications for up to 6 Gbps per channel. The connector accepts multiple transceivers per INF-8074i and combines, transmits, and receives functions in a low-cost, compact format. The assemblies are designed to maximize valuable space on the PCB.



SJT Data Connector

Data connector according to VG96912, shielded, in size 12 including backshell for High-Speed and Ethernet applications up to CAT6_A (10Gbit/s according to DIN EN 50173-1, up to 500 MHz).



SK Series - Sockets

With designs supporting pitches down to 0.4mm and speeds up to 40GHz, the SK series sockets are being used in cutting-edge BGA, LGA, and other small form factor IC applications. These sockets offer cycle lives of thousands of mating cycles. The electrical reliability & performance of our sockets can meet the most demanding application needs.



Slim Cool Edge 0.65mm Hybrid Power & Signal Connectors

Slim Cool Edge Hybrid Power & Signal connectors provide a one-piece high speed and high power card-edge package. These connectors offer cost-competitive and high-density solutions. These versatile solutions based on a 0.65mm signal pitch design offer multiple BTB configurations like right angle, mezzanine, and coplanar. The connectors are designed as Open Pin Field & are hot-plug capable.



SlimSAS™

PROVEN, HIGH SPEED, NEXT-GENERATION SAS-4 INTERFACE SlimSAS™ connectors address issues in next-generation storage devices such as bulk cable form factor restrictions and the introduction of multi-lane storage devices. SlimSAS™ connector is a 0.60mm pitch interconnect system that offers superior signal integrity performance over standard Mini-SAS solutions.



SlimSAS™ Low Profile Connectors - U10 Series

Amphenol has developed SlimSAS™ low profile connector which is used in the application of UPI1.0, 11.2GT/s, 24Gb/s SAS signal, or 16GT/s PCIe® signal. With 0.60mm contact pitch, Low Profile (LP) SlimSAS™ solutions are smaller than mainstream connectors in current market to save space in end devices. LP SlimSAS™ was also called SlimSAS™ LP.



TVμCom 10 Gb+

TVμCom-10Gb+ combines 10 Gb/s Ethernet speed of the classic μCom-10Gb+ with the ruggedness of 38999 Series III shell. TVμCom-10Gb+ exceeds 10Gb/s according to the IEEE 802.3an-2006, 10GBase-T standard, and the 38999 series III size 11 shell provides environmental resistance similar to MIL-DTL-38999 Series III.



UltraPort™ QSFP+

Amphenol's UltraPort™ QSFP+ interconnect system comprises a 38-position, 0.8mm pitch connector built for use in high-speed serial applications. Each port offers 4 channels to increase port density which allows more board real estate and cost-optimized solutions. The UltraPort™ QSFP+ connector supports next-generation 100G+ applications and transmits up to 28 Gb/s per channel.



UltraPort™ SFP+

Amphenol's UltraPort™ SFP+ interconnect system comprises of a 20-position hot-swappable I/O connector enclosed in a metal cage mounted to a host PCB. It supports 28Gb/s applications with backward compatibility for next-generation Ethernet and Fibre Channel applications. UltraPort™ SFP+ connector shares the same unique mating interface and EMI cage dimensions as the SFP+ form factor.



X2

DESIGNED TO ACHIEVE 56G DATA RATE REQUIREMENTS X2's upgraded platform maintains backward mating interface compatibility with existing XCede® products while offering new backplane configurations. Mid-plane-based orthogonal solutions are available for 6-Pair along with the others, supporting both 85Ω and 100Ω to meet a wide variety of application needs, including Ethernet and PCI.



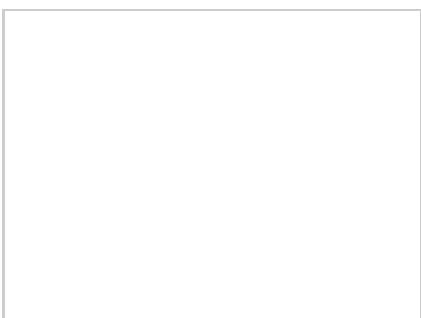
XCede I/O

The XCede® I/O interconnect system is comprised of a 32-position, variable pitch connector built for use in high-speed serial applications. Each port offers 4 channels to increase port density which contributes to more board real estate and immense cost savings. The XCede® I/O connector supports next-generation 100G+ applications and transmits up to 25 Gbps/serial-lane.



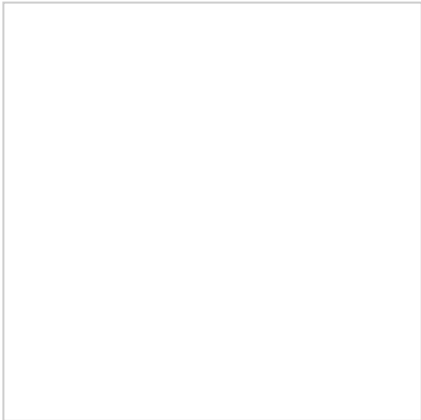
XCede Plus Backplane Connector

DESIGNED TO ACHIEVE 32G DATA RATE REQUIREMENTS XCede Plus leverages the same core technologies as XCede with improved signal integrity performance while maintaining backward mating interface compatibility with existing XCede products.



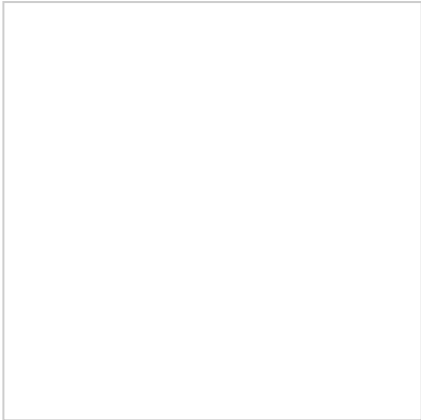
XCede® Backplane Connector

ENABLING FUTURE DATA RATES While maintaining the same mating interfaces, this connector design provides designers with readily available 85Ω and 100Ω solutions to meet a wide variety of application needs, including Ethernet and PCI.



XCede® HD

XCede® HD backplane connector achieves high performance (up to 20 Gb/s) in a Hard Metric form factor. Offering a linear density of up to 84 differential pairs per inch (33 differential pairs per centimeter), the XCede® HD connector meets the requirements of high-density architectures with a 35% increase in density as compared to standard XCede®.



XCede® HD2

DESIGNED TO ACHIEVE 56G DATA RATE REQUIREMENTS WITH HIGHER DENSITY While maintaining the same mating interfaces with XCede® HD and XCede® HD Plus, this connector provides developers with a readily available robust solution for tighter card pitches and chassis designs where space requirements and density are critical.



High Speed Connectors



XCede® HD Plus

The XCede® HD Plus backplane connector achieves high performance (up to 28+ Gb/s) in a Hard Metric form factor. Offering a linear density of up to 84 differential pairs per inch (33 differential pairs per centimeter), the XCede® HD Plus connector meets the high-density needs of today's challenging architectures.



XFP

XFP is a 30pos 0.8mm pitch SMT receptacle designed to support 10 Gigabit Fibre Channel and Gigabit Ethernet with the ability to extend performance to 14 Gbps. It is constructed from a metal frame and the cage assembly is to be bezel-mounted to an I/O panel with compliant pins for pressing onto the host PCB. Its single row cage configuration requires less space & is cost-optimized.